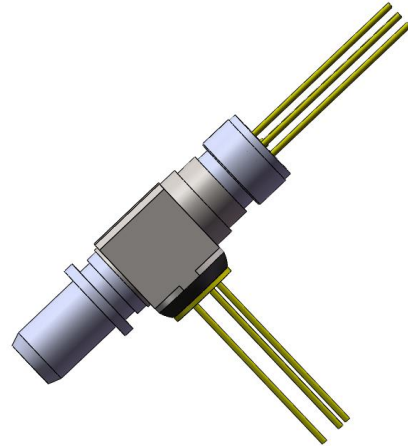


ETRRDATxxFxWT3FxxxG

With 1270nm 10G DFB laser diode and 1577nm 10G APD-TIA transmission



Features

- ◆ Coaxial package
- ◆ InGaAsP/InP MQW-DFB laser diode
- ◆ Low threshold, high slope efficiency and high output power
- ◆ High sensitive APD-TIA
- ◆ ROHS compliant products available

Applications

- ◆ 10GbE application
- ◆ symmetry 10G EPON ONU

Performance specification

Absolute maximum ratings(Tc=25°C,unless otherwise noted) ^{*Note1}

Parameter	Symbol	Min.	Max.	Unit
Storage temperature	Tstg	-40	85	°C
Operating case temperature	Topr	-40	85	°C
Storage and operating humidity	--	--	85	%
LD reverse voltage	V _{RL}	--	2	V
LD forward current	I _{FL}	--	120	mA
LD optical output power	P _O	--	10	dBm
MPD reverse voltage	V _{RD}	--	6	V
MPD forward current	I _{FD}	--	1	mA

APD supply voltage	V_{apd}	--	V_{br}	V
APD forward current	I_{FD}	--	2	mA
APD reverse current	I_{FD}	--	2	mA
TIA supply voltage	V_{CC}	-0.7	5	V
Lead soldering (temperature)/(time)	--	--	260/10	°C/Sec

*Note1: Exceeding any one of these values may destroy the device immediately.

Transmitter optical and electrical characteristics

(Unless specified else, the specifications below are defined at $T_c=25^\circ\text{C}$)

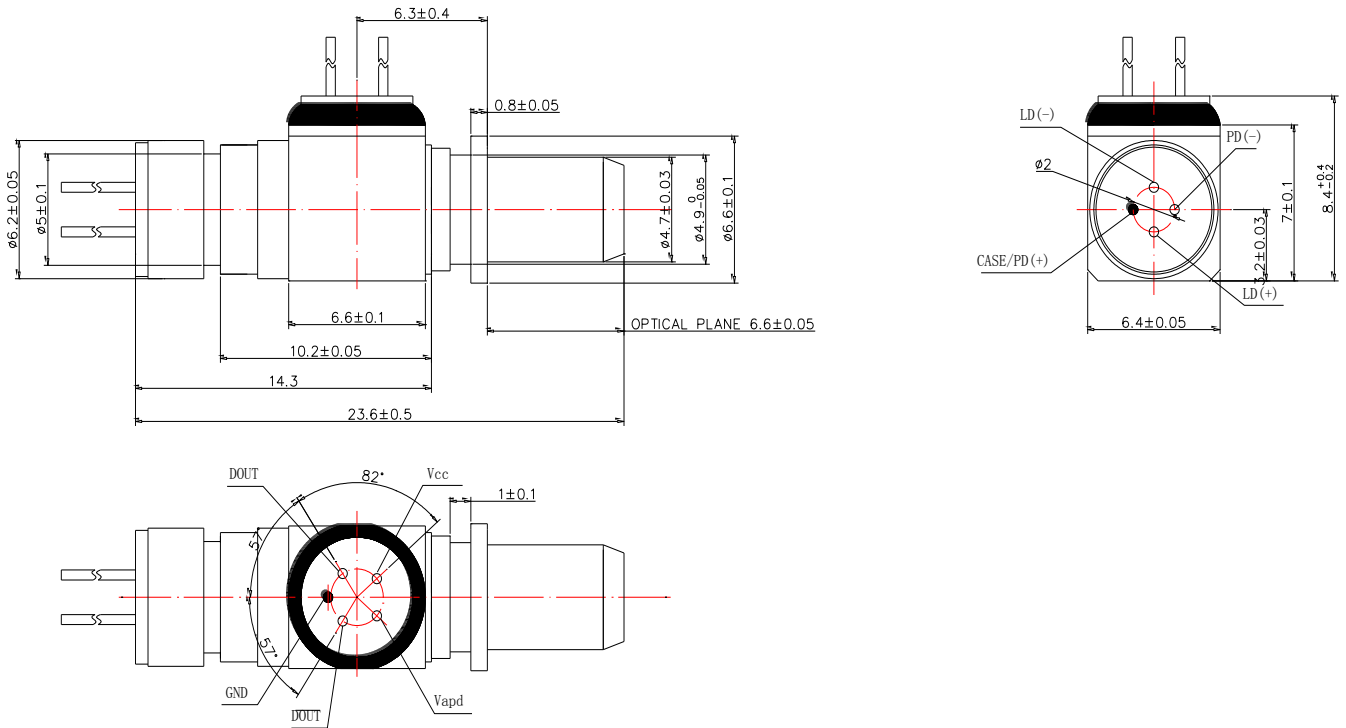
Parameter	Symbol	Min	Typ	Max	Unit	Condition
Threshold current	I_{th}	--	7	10	mA	CW
Laser output optical power	P_f	3.2	--	5	mW	CW, $I_f=I_{th}+20\text{mA}$
Slope efficiency	SE	0.16	--	0.25	W/A	CW, $I_f=I_{th}+20\text{mA}$
Optical wavelength	λ	1260	1270	1280	nm	CW, $I_f=I_{th}+20\text{mA}$
Operating voltage	V_f	--	1.2	1.7	V	CW, $I_f=I_{th}+20\text{mA}$
Spectrum width (-20dB)	$\Delta\lambda$	--	--	1.0	nm	CW, $I_f=I_{th}+20\text{mA}$
Side mode suppression ratio	SMSR	35	40	--	dB	CW, $I_f=I_{th}+20\text{mA}$
Monitor current	I_m	0.08	--	0.8	mA	CW, $I_f=I_{th}+20\text{mA}$
Monitor dark current	I_d	--	--	100	nA	$V_{rp}=5\text{V}$
Tracking Error	TE	-1.5		+1.5	dB	-40~85°C

Receiver optical and electrical characteristics

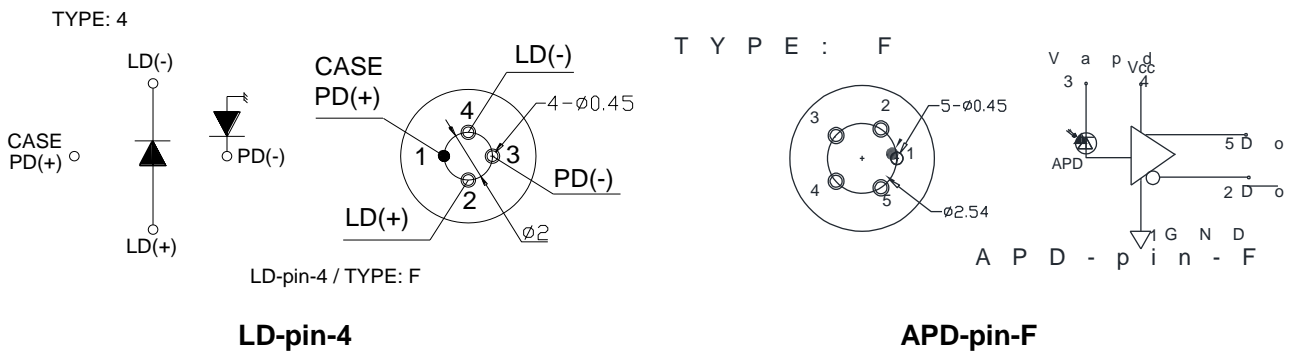
(Unless specified else, the specifications below are defined at $T_c=25^\circ\text{C}$)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Supply voltage	V_{cc}	3.0	3.3	3.6	V	
Breakdown voltage	V_{br}	20	34	40	V	$I_d=10\mu\text{A}$
Dark current	I_d	--	--	100	nA	V_{op}
Receiving wavelength	λ	1575	1577	1580	nm	
Optical sensitivity	S	--	--	-29.5	dBm	$\lambda=1577\text{nm}, 10.3\text{Gbps},$ $PRBS=2^{31}-1, BER<10^{-3}, \text{NRZ},$
Overload power	P_{load}	-7	--	--	dBm	
TIA supply current	I_{cc}	22	--	50	mA	$V_{cc}=3.3\text{V}$
Temp. coefficient of V_{br}	γ	0.4		0.6	V/°C	$I_d=10\mu\text{A}, \phi$ $e=0\mu\text{W}-40\sim+85^\circ\text{C}$
Optical crosstalk	X_{opt}	--	--	-40	dB	$\lambda=1260\sim1510\text{nm}$ & $1600\sim1630\text{nm}$

Package dimension ^{*Note2}

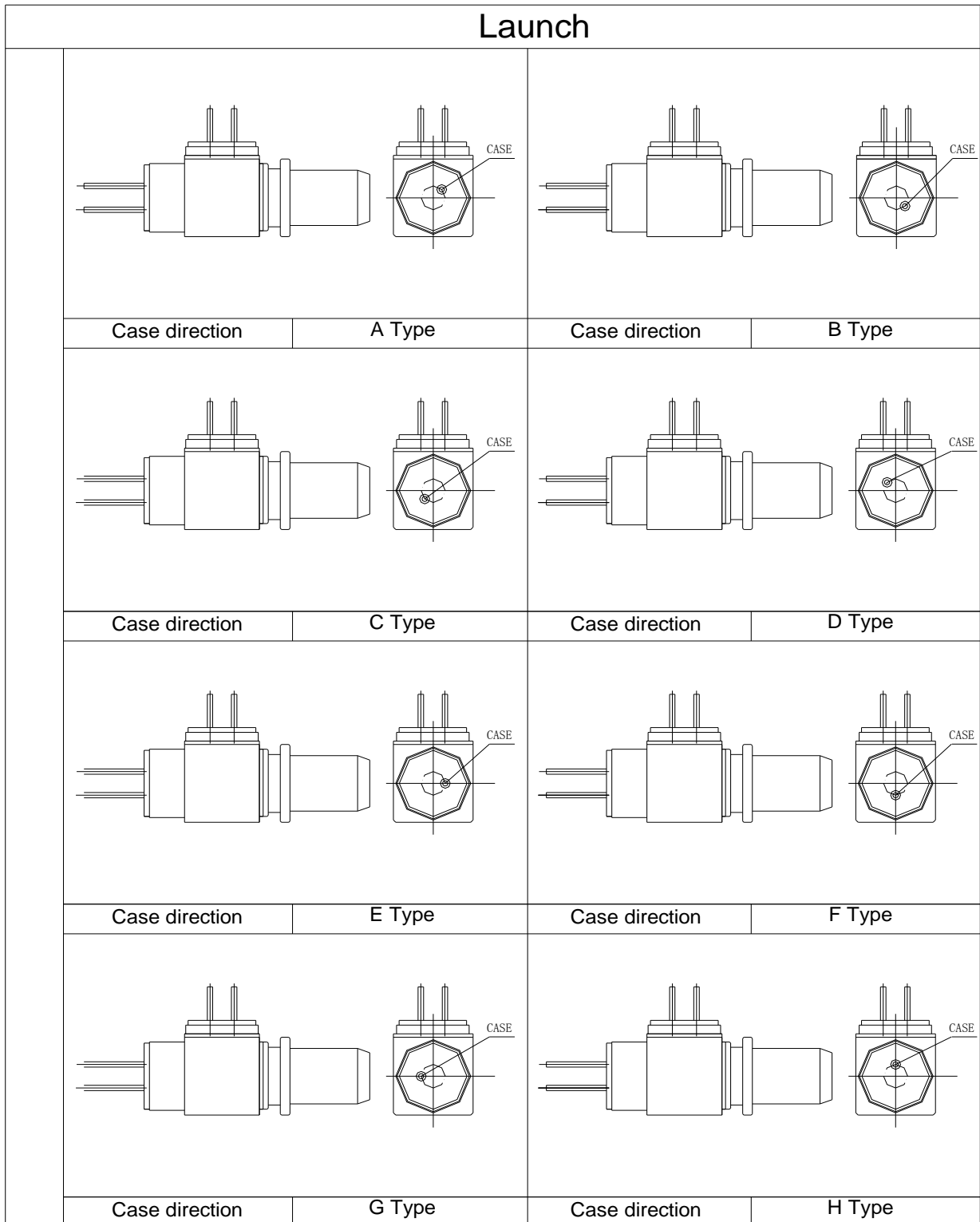


Pin assignment



Note2: PIN direction and laser mark can be customized.

TX pin order code*Note3.4.5



Note3: This picture is for pluggable, receptacle BIDI chip PIN package direction's reference

Note4: This picture is suitable for RX Pin direction comparison .

Note5: The package direction is described as "x-x" For example "A-B", "A" is TX chip Pin direction, "B" is RX chip Pin direction.

RX pin order code

Receive			
Case direction	A Type	Case direction	B Type
Case direction	C Type	Case direction	D Type
Case direction	E Type	Case direction	F Type
Case direction	G Type	Case direction	H Type
Case direction		Case direction	
Case direction		Case direction	
Case direction		Case direction	
Case direction		Case direction	

Ordering information (standard version) ^{*Note6}

Part No	Laser type	transmitter/receiver
ETRRDAT35FxWT3FxxxG	DFB	1270T/1577R

Note6: For more ordering information, please refer to nomenclature or contact EOPTOLINK sales.

ETRR

A B C D E F G H I J K L M N

Code	Parameter	Detailed description							
A	Laser type	D=DFB LD							
B	Launch wavelength	A=1270nm							
C	Launch data rate	T=10Gbps							
D	Output power	35=3.2~5mW				xx=Customization			
E	TX pin type	F=LD-pin-4							
F	TX chip type	x=A~Z(No choice)							
G	Receiver wavelength	W=1577nm							
H	Receiver data rate	T=10Gbps							
I	TIA voltage	3=3.3V							
J	RX pin type	F=APD-TIA-pin-F							
K	RX chip type	x=A~Z(No choice)							
L	TX pin package direction	A	B	C	D	E	F	G	H
M	RX pin package direction	A	B	C	D	E	F	G	H
N	Isolator	Blank=None				G=with I			

Precaution

- (1) The modules should be handled in the same manner as ordinary semiconductor devices to prevent the electro-static damages. For safe keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

Obtaining document

You can visit our website:

<http://www.eoptolink.com>

Or contact Eoptolink Technology Inc., Ltd. listed at the end of the documentation to get the latest documentation.

Revision history

Revision	Initiated	Reviewed	Approved	Revision history	Release date
Va-1	James.liu	Zore.Zhao Kelly.cao		Initial	2019-11-09

Notice:

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